

BUK6D43-60E,115-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^a	Q_g (Typ.)
60	0.019 at $V_{GS} = 10$ V	14	7.2 nC
	0.021 at $V_{GS} = 4.5$ V	11	

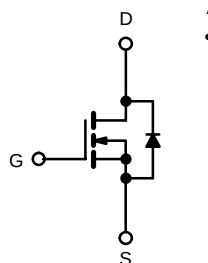
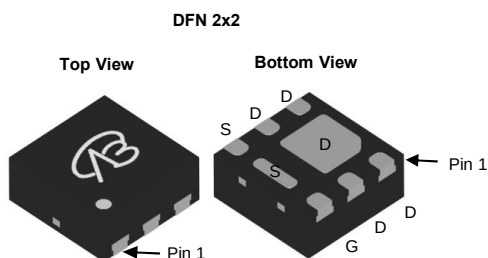
FEATURES

- Halogen-free
- Trench Power MOSFET
- Optimized for High-Side Synchronous Rectifier Operation
- 100 % R_g Tested
- 100 % UIS Tested



APPLICATIONS

- Notebook CPU Core
- High-Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150$ °C)	$T_C = 25$ °C	14	A
	$T_C = 70$ °C	11	
	$T_A = 25$ °C	5.5 ^{b, c}	
	$T_A = 70$ °C	2.8 ^{b, c}	
Pulsed Drain Current	I_{DM}	42	A
Continuous Source-Drain Diode Current	$T_C = 25$ °C	4.8	
	$T_A = 25$ °C	2.0 ^{b, c}	
Single Pulse Avalanche Current	I_{AS}	20	mJ
Avalanche Energy	E_{AS}	21	
Maximum Power Dissipation	$T_C = 25$ °C	4.1	W
	$T_C = 70$ °C	2.5	
	$T_A = 25$ °C	2.2 ^{b, c}	
	$T_A = 70$ °C	1.3 ^{b, c}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R_{thJA}	39	55	°C/W
Maximum Junction-to-Foot (Drain)	R_{thJF}	25	29	

Notes:

a. Base on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. $t = 10$ s.

d. Maximum under Steady State conditions is 85 °C/W.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	60			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		26		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 6		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		1.5		V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 4 8 V, V _{GS} = 0 V			1	μA
		V _{DS} = 4 8 V, V _{GS} = 0 V, T _J = 55 °C			10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	20			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A		0.019		Ω
		V _{GS} = 4.5 V, I _D = 9 A		0.021		
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 10 A		50		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		1800		pF
Output Capacitance	C _{oss}			165		
Reverse Transfer Capacitance	C _{rss}			73		
Total Gate Charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A		15	23	nC
		V _{DS} = 15 V, V _{GS} = 5 V, I _D = 10 A		6.8	10.2	
Gate-Source Charge	Q _{gs}			2.5		
Gate-Drain Charge	Q _{gd}			2.3		
Gate Resistance	R _g	f = 1 MHz	0.36	1.8	3.6	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15 V, R _L = 1.4 Ω I _D ≅ 9 A, V _{GEN} = 4.5 V, R _g = 1 Ω		16	23	ns
Rise Time	t _r			12	16	
Turn-Off Delay Time	t _{d(off)}			16	22	
Fall Time	t _f			10	18	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15 V, R _L = 1.4 Ω I _D ≅ 9 A, V _{GEN} = 10 V, R _g = 1 Ω		8	16	
Rise Time	t _r			10	20	
Turn-Off Delay Time	t _{d(off)}			16	22	
Fall Time	t _f			8	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			14	A
Pulse Diode Forward Current ^a	I _{SM}				42	
Body Diode Voltage	V _{SD}	I _S = 9 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 9 A, dI/dt = 100 A/μs, T _J = 25 °C		15	30	ns
Body Diode Reverse Recovery Charge	Q _{rr}			6	12	nC
Reverse Recovery Fall Time	t _a			8		ns
Reverse Recovery Rise Time	t _b			7		

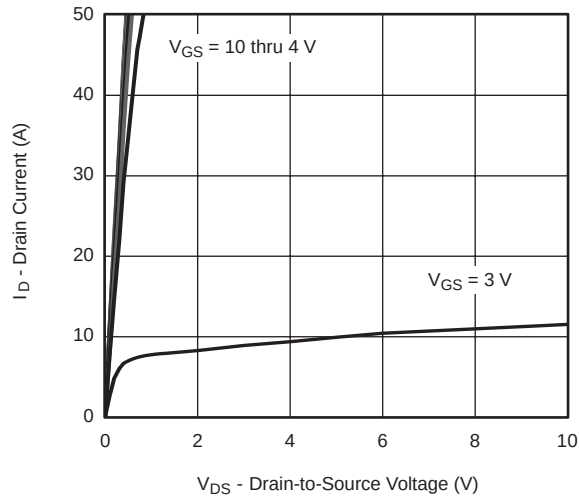
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

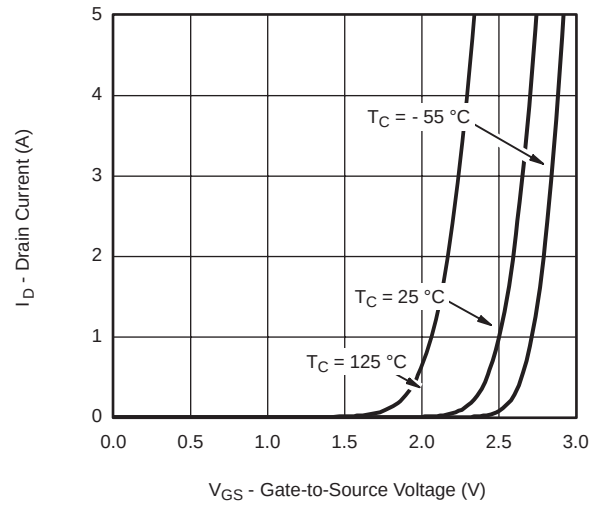
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

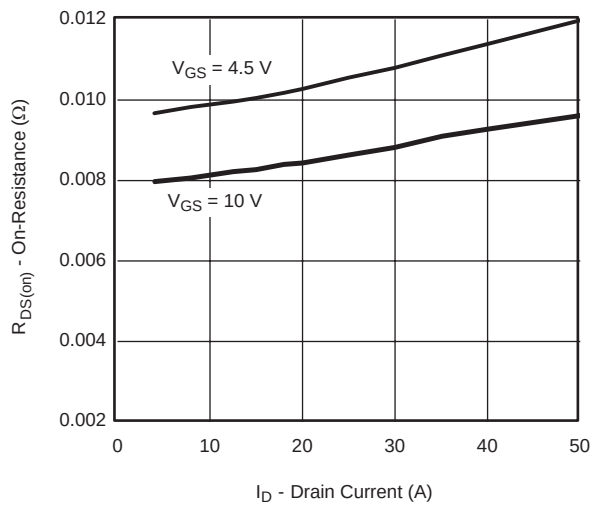
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



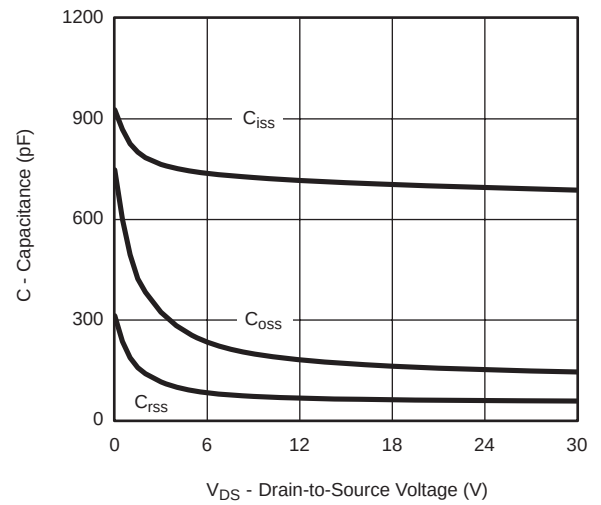
Output Characteristics



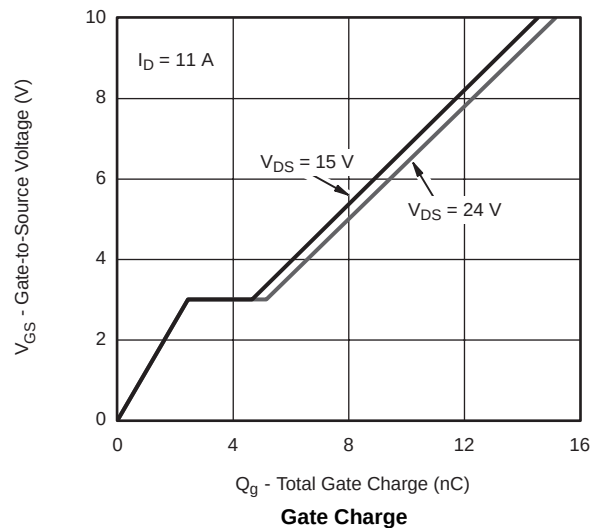
Transfer Characteristics



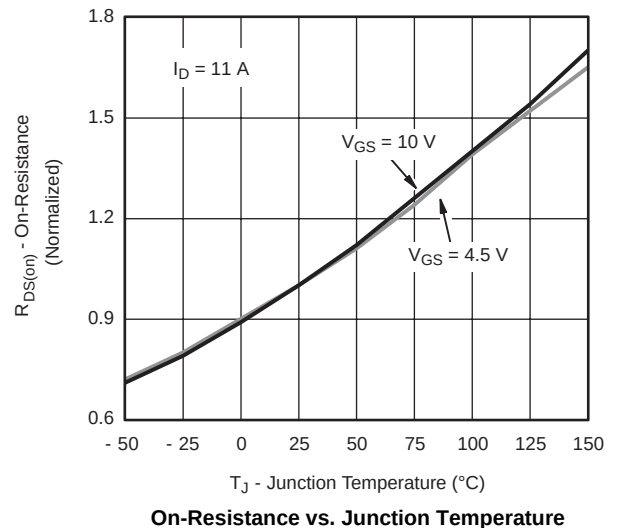
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

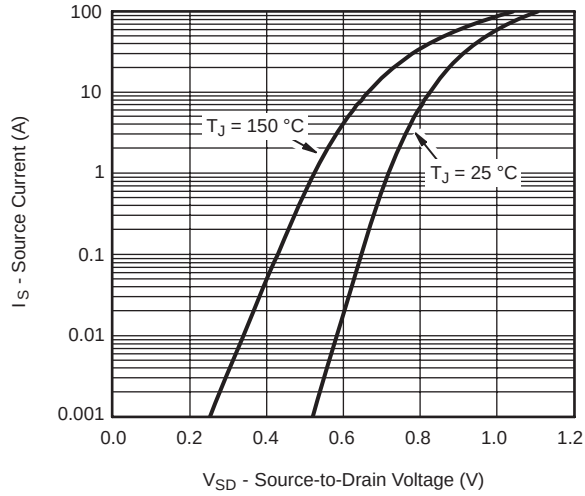


Gate Charge

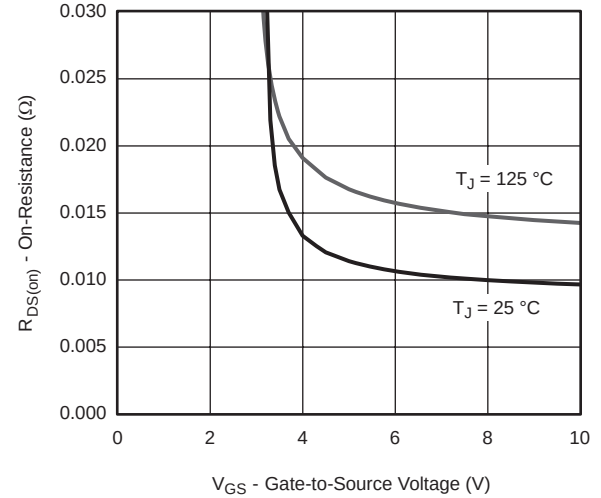


On-Resistance vs. Junction Temperature

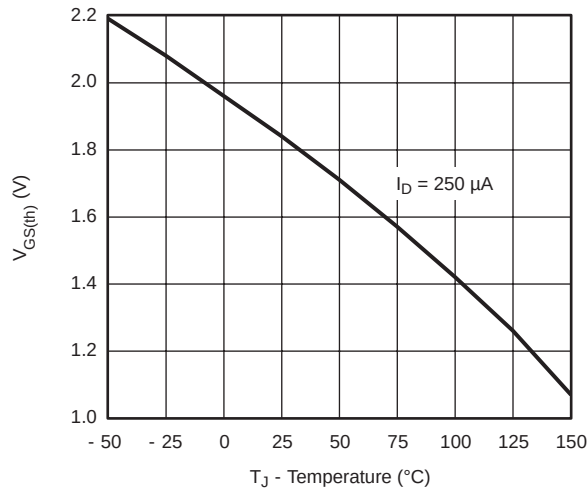
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



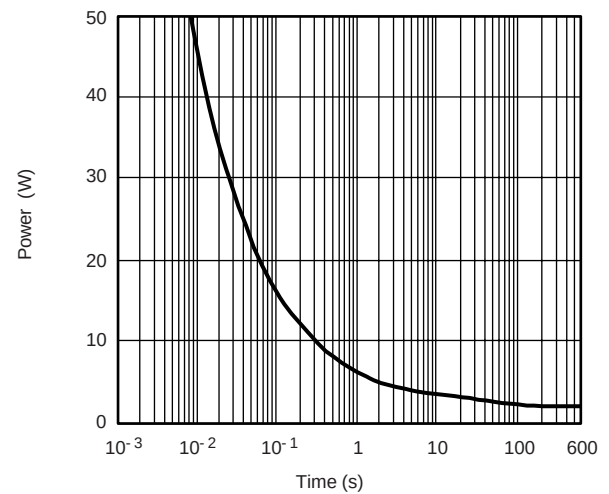
Source-Drain Diode Forward Voltage



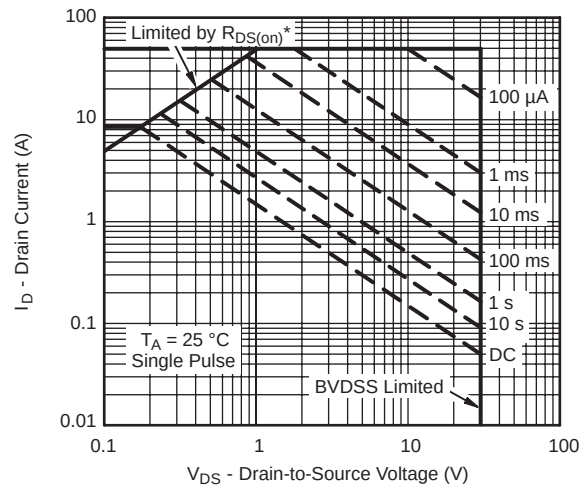
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



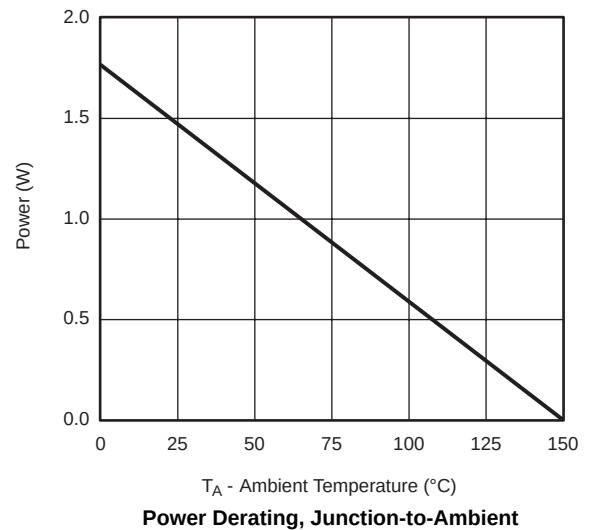
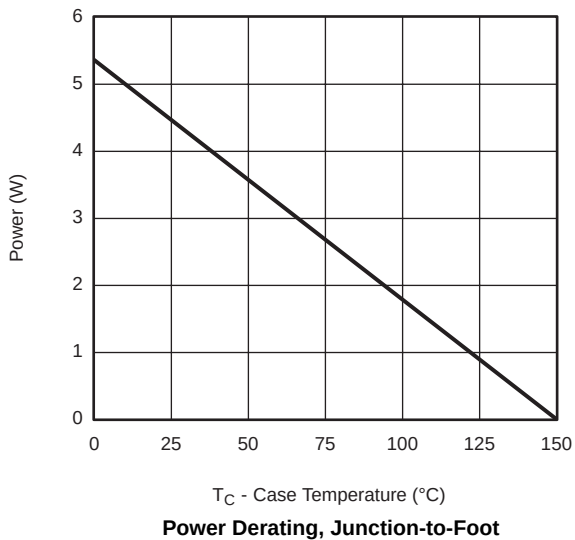
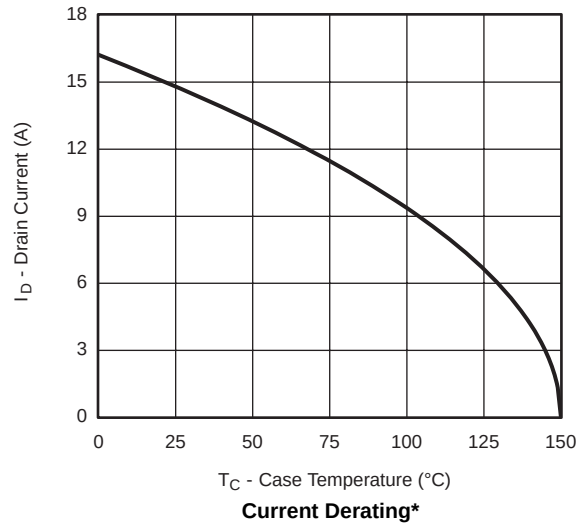
Single Pulse Power, Junction-to-Ambient



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

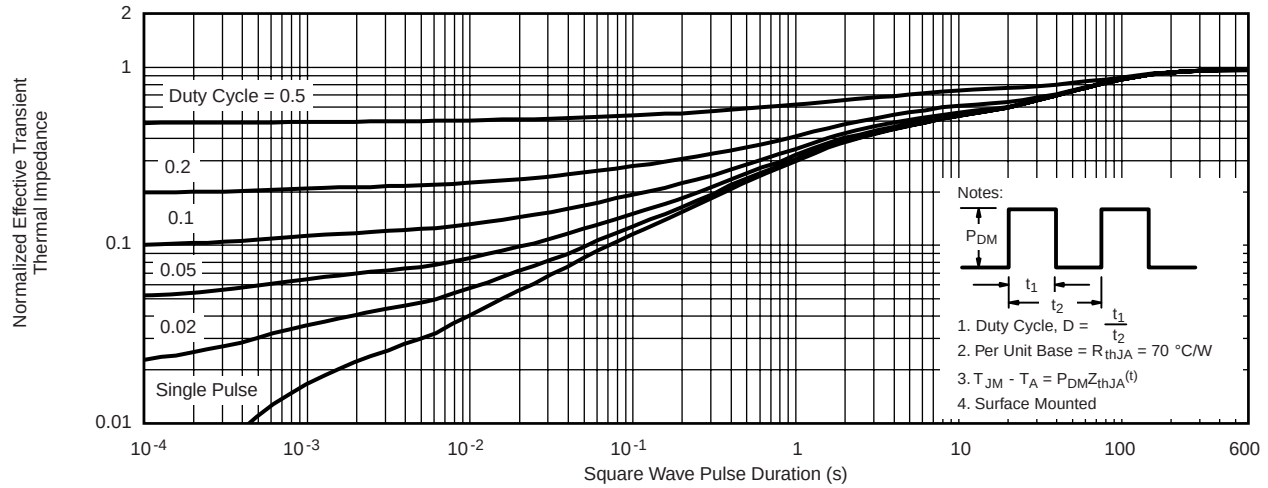
Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

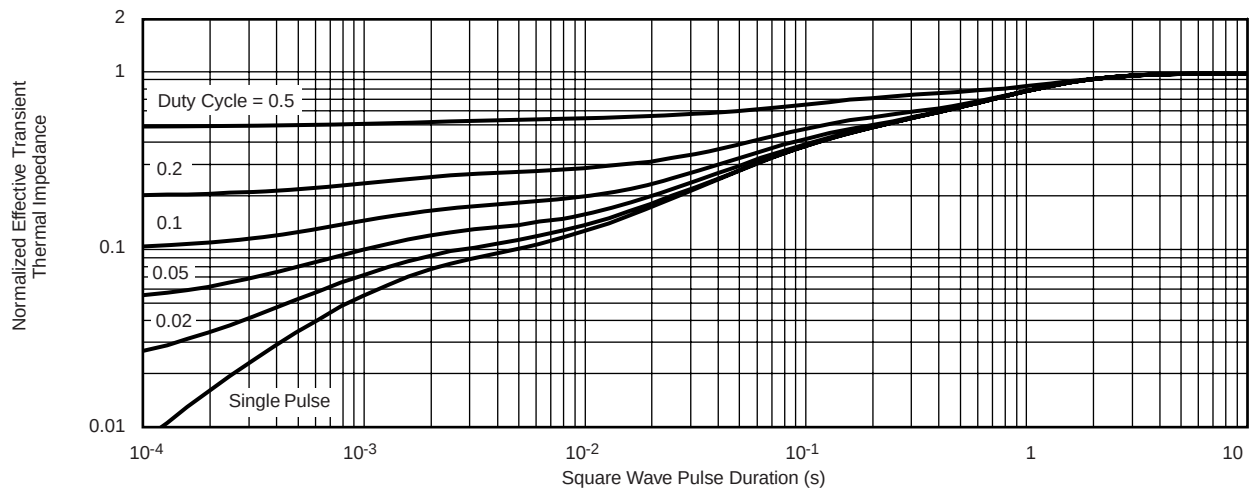


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

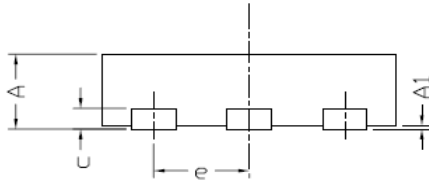
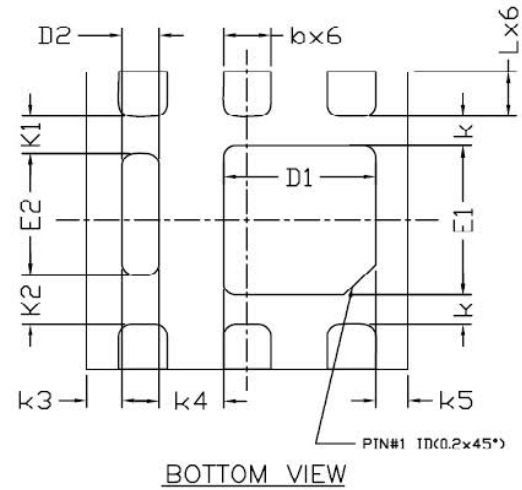
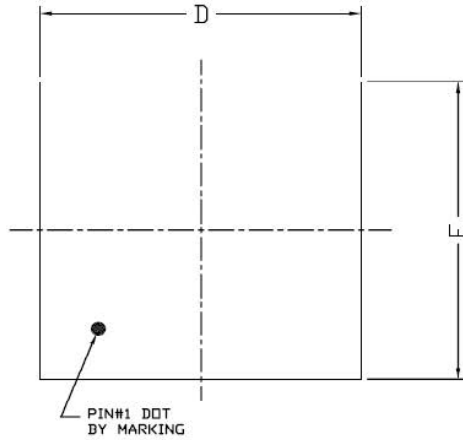


Normalized Thermal Transient Impedance, Junction-to-Ambient

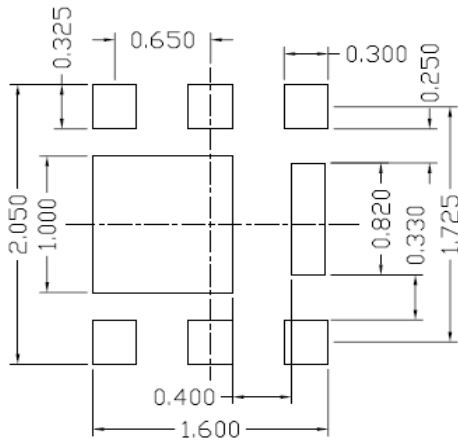


Normalized Thermal Transient Impedance, Junction-to-Foot

DFN2x2 _6L_EP1_S PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



UNIT: mm

NOTE

1. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
A1	0.00	—	0.05	0.000	—	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.152 REF			0.006 REF		
D	1.90	2.00	2.10	0.075	0.079	0.083
D1	0.85	0.95	1.05	0.033	0.037	0.041
D2	0.13	0.23	0.33	0.005	0.009	0.013
E	1.90	2.00	2.10	0.075	0.079	0.083
E1	0.90	1.00	1.10	0.035	0.039	0.043
E2	0.72	0.82	0.92	0.028	0.032	0.036
e	0.65 BSC			0.026 BSC		
K	0.20 BSC			0.008 BSC		
K1	0.25 BSC			0.010 BSC		
K2	0.33 BSC			0.013 BSC		
K3	0.22 BSC			0.009 BSC		
K4	0.40 BSC			0.016 BSC		
K5	0.20 BSC			0.008 BSC		
L	0.25	0.30	0.35	0.010	0.012	0.014

Figure 1 is a technical drawing of a mechanical part, labeled '1'. The drawing shows the front and side views of the part, with dimensions in millimeters (mm) and inches (in). The part is a complex, symmetrical component with a central rectangular body and several smaller rectangular features. Dimensions are provided for overall size, individual features, and spacing between features.

Dimensions (mm / in):

- Overall width: 9.50 (0.037)
- Overall height: 2.200 (0.087)
- Top flange width: 0.300 (0.012)
- Top flange height: 0.350 (0.014)
- Central body width: 0.650 (0.026)
- Central body height: 1.500 (0.059)
- Bottom flange width: 0.300 (0.012)
- Bottom flange height: 0.350 (0.014)
- Side flange width: 0.650 (0.026)
- Side flange height: 0.350 (0.014)
- Internal feature width: 0.235 (0.009)
- Internal feature height: 0.475 (0.019)
- Internal feature spacing: 0.550 (0.022)
- Internal feature offset: 0.275 (0.011)
- Internal feature depth: 0.870 (0.034)
- Internal feature offset: 0.355 (0.014)

Dimensions in mm/(Inches)

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